

## N-channel 600 V, 0.110 Ω typ., 24 A MDmesh<sup>™</sup> DM2 Power MOSFET in TO-220FP package

Datasheet - production data

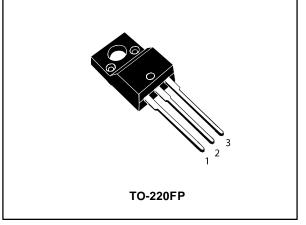
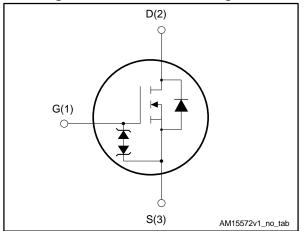


Figure 1: Internal schematic diagram



### **Features**

Order code	V <sub>DS</sub> @ T <sub>Jmax</sub> .	RDS(on) max.	ID
STF33N60DM2	650 V	0.130 Ω	24 A

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### **Applications**

• Switching applications

### Description

This high voltage N-channel Power MOSFET is part of the MDmesh<sup>TM</sup> DM2 fast recovery diode series. It offers very low recovery charge ( $Q_{rr}$ ) and time ( $t_{rr}$ ) combined with low  $R_{DS(on)}$ , rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

#### Table 1: Device summary

Order code	Marking	Package	Packing
STF33N60DM2	33N60DM2	TO-220FP	Tube

DocID026861 Rev 2

1/13

This is information on a product in full production.

### Contents

### Contents

1	Electric	al ratings	3
2	Electric	al characteristics	4
	2.1	Electrical characteristics (curves)	6
3	Test cir	cuits	8
4	Packag	e information	9
	4.1	TO-220FP package information	10
5	Revisio	on history	12



## 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
Vgs	Gate-source voltage	±25	V
1-	Drain current (continuous) at T <sub>case</sub> = 25 °C	24	۸
ID	Drain current (continuous) at T <sub>case</sub> = 100 °C	15.5	A
Idм <sup>(1)</sup>	Drain current (pulsed)	96	А
P <sub>TOT</sub>	Total dissipation at $T_{case} = 25 \text{ °C}$	35	W
dv/dt <sup>(2)</sup>	Peak diode recovery voltage slope	50	V/ns
dv/dt <sup>(3)</sup>	MOSFET dv/dt ruggedness	50	v/ns
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; $T_C$ = 25 °C)	2500	V
T <sub>stg</sub>	Storage temperature range	55 to 150	°C
Tj	Operating junction temperature range	-55 to 150	C

#### Notes:

 $^{\left( 1\right) }$  Pulse width is limited by safe operating area.

 $^{(2)}$  Isp  $\leq 24$  A, di/dt=900 A/µs; Vps peak < V(BR)pss, Vpp = 400 V.

 $^{(3)}$  V<sub>DS</sub>  $\leq$  480 V.

### Table 3: Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj</sub> -case	Thermal resistance junction-case	3.6	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient	62.5	C/W

#### Table 4: Avalanche characteristics

Symbol	Parameter		Unit
IAR	Avalanche current, repetitive or not repetitive (Pulse width limited by $T_{jmax}$ )	5.5	А
E <sub>AS</sub>	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$ , $V_{DD} = 50$ V)	570	mJ



## 2 Electrical characteristics

(T<sub>case</sub> = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA	600			V
I <sub>DSS</sub> Zero gate voltage drain current	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 600 V			1		
	0 0	$V_{GS} = 0 V, V_{DS} = 600 V,$ $T_{case} = 125 °C^{(1)}$			100	μA
lgss	Gate-body leakage current	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			±10	μΑ
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	3	4	5	V
R <sub>DS(on)</sub>	Static drain-source on- resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 12 \text{ A}$		0.110	0.130	Ω

#### Notes:

<sup>(1)</sup>Defined by design, not subject to production test.

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	1870	-	
Coss	Output capacitance	V <sub>DS</sub> = 100 V, f = 1 MHz,	-	87	-	рF
C <sub>rss</sub>	Reverse transfer capacitance	V <sub>GS</sub> = 0 V	-	2	-	P1
Coss eq. <sup>(1)</sup>	Equivalent output capacitance	$V_{DD} = 480 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	157	-	рF
Rg	Intrinsic gate resistance	f = 1 MHz, I <sub>D</sub> = 0 A	-	4.5	-	Ω
Qg	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 24 \text{ A},$	-	43	-	
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 10 V (see Figure 15: "Test circuit for gate charge	-	9.8	-	nC
Q <sub>gd</sub>	Gate-drain charge	behavior")	-	21	-	

#### Table 6: Dynamic

#### Notes:

 $^{(1)}$  Coss eq. is defined as a constant equivalent capacitance giving the same charging time as Coss when VDs increases from 0 to 80% VDss.

Table	7:	Switching	times
Table		owncoming	umes

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 12 \text{ A}$	-	17	-	
tr	Rise time	$R_G = 4.7 \Omega$ , $V_{GS} = 10 V$ (see Figure 14: "Test circuit for resistive load switching	-	8	-	
td(off)	Turn-off delay time		-	62	-	ns
t <sub>f</sub>	Fall time	times" and Figure 19: "Switching time waveform")	-	9	-	



#### Electrical characteristics

Symbol	Parameter	e 8: Source-drain diode Test conditions	Min.	Typ.	Max.	Unit
Isp	Source-drain current		-	- 71	24	A
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		96	А
Vsd <sup>(2)</sup>	Forward on voltage	Vgs = 0 V, Isd = 24 A	-		1.6	V
trr	Reverse recovery time	I <sub>SD</sub> = 24 A, di/dt = 100 A/µs,	-	120		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ (see Figure 16:	-	0.53		μC
I <sub>RRM</sub>	Reverse recovery current	"Test circuit for inductive load - switching and diode recovery times")	-	8.8		А
trr	Reverse recovery time	I <sub>SD</sub> = 24 A, di/dt = 100 A/µs,	-	316		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, \text{ T}_{\text{j}} = 150 \text{ °C}$ (see Figure 16: "Test circuit for	-	2.85		μC
Irrm	Reverse recovery current	inductive load switching and diode recovery times")	-	18		A

#### Notes:

<sup>(1)</sup> Pulse width is limited by safe operating area.

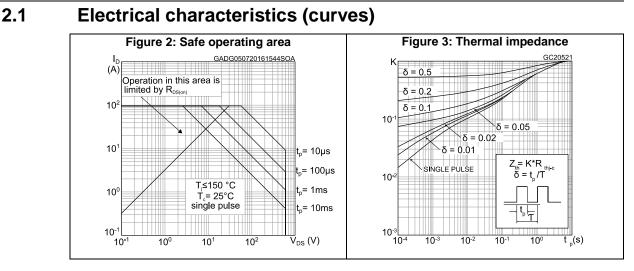
 $^{(2)}$  Pulse test: pulse duration = 300  $\mu s,$  duty cycle 1.5%.

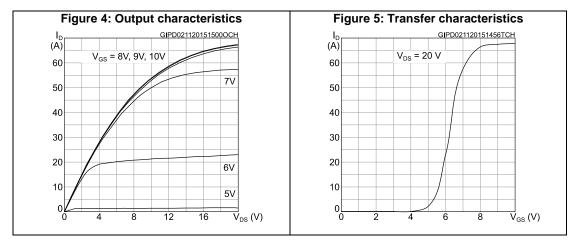
#### Table 9: Gate-source Zener diode

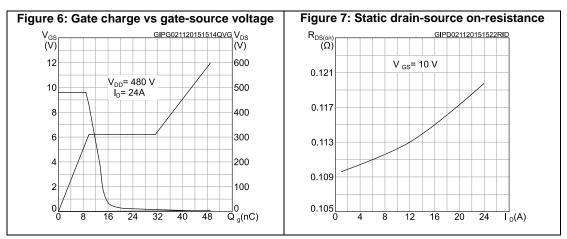
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)</sub> GSO	Gate-source breakdown voltage	$I_{GS} = \pm 250 \ \mu A, I_D = 0 \ A$	±30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.





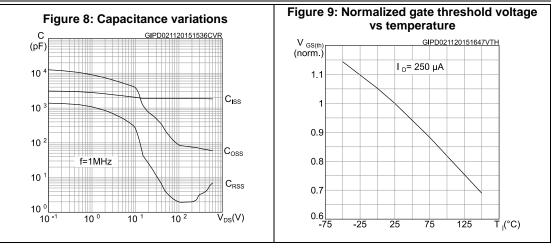


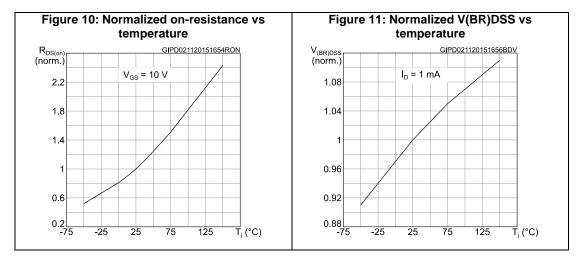


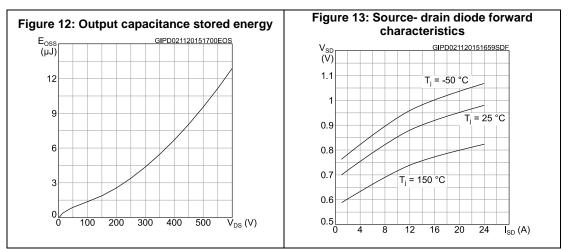
DocID026861 Rev 2



#### **Electrical characteristics**

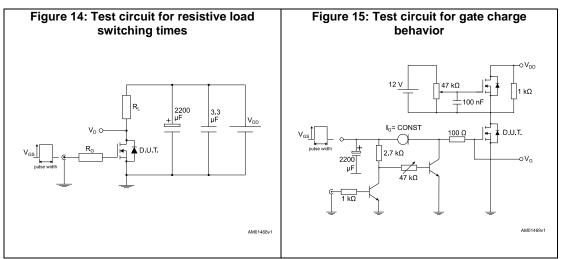


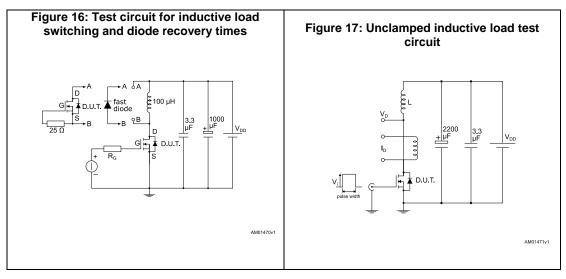


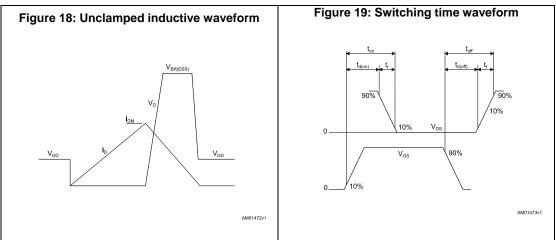


57

### 3 Test circuits







DocID026861 Rev 2

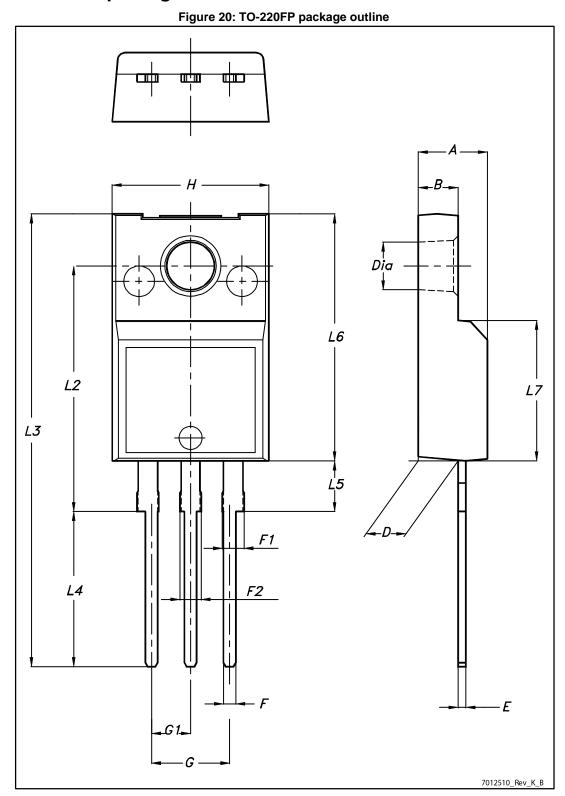


### 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.



## 4.1 TO-220FP package information



DocID026861 Rev 2



### Package information

DM2			Package information	
Table 10: TO-220FP package mechanical data				
Dim.	mm			
	Min.	Тур.	Max.	
A	4.4		4.6	
В	2.5		2.7	
D	2.5		2.75	
E	0.45		0.7	
F	0.75		1	
F1	1.15		1.70	
F2	1.15		1.70	
G	4.95		5.2	
G1	2.4		2.7	
Н	10		10.4	
L2		16		
L3	28.6		30.6	
L4	9.8		10.6	
L5	2.9		3.6	
L6	15.9		16.4	
L7	9		9.3	
Dia	3		3.2	



## 5 Revision history

Table 11: Document revision history

Date	Revision	Changes	
04-Sep-2014	1	First release.	
05-Jul-2016	2	Document status promoted from preliminary to production data. Updated title and features in cover page. Updated Section 1: "Electrical ratings" and Section 2: "Electrical characteristics". Added Section 2.1: "Electrical characteristics (curves)". Minor text changes.	



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